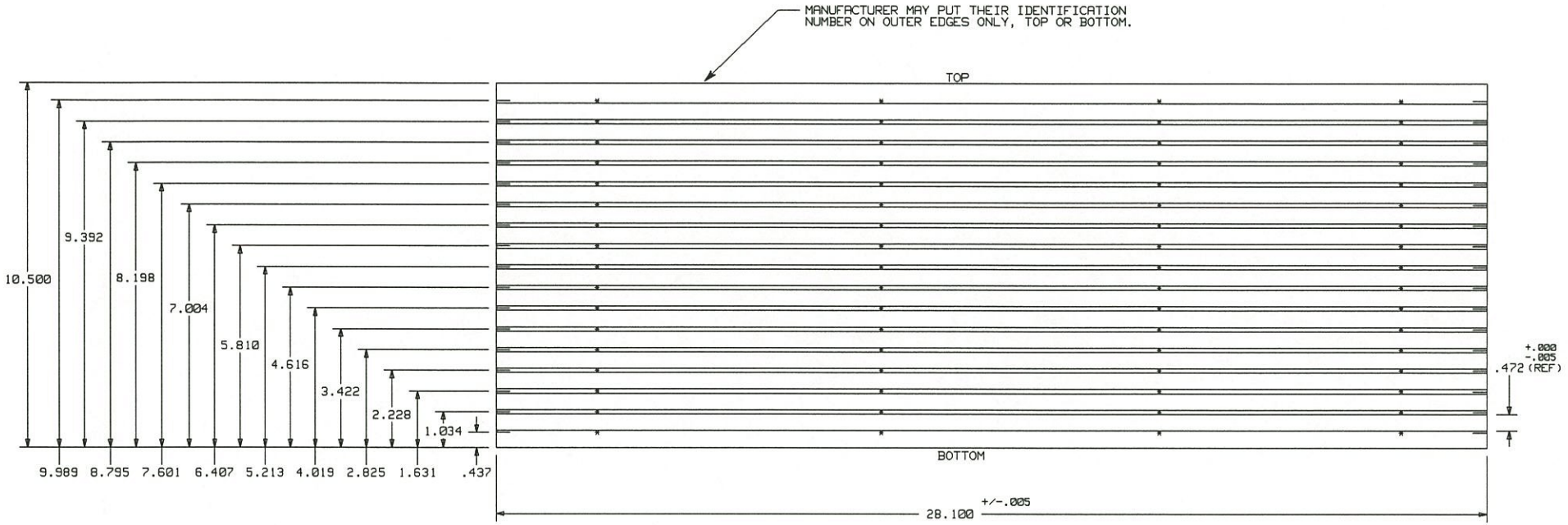
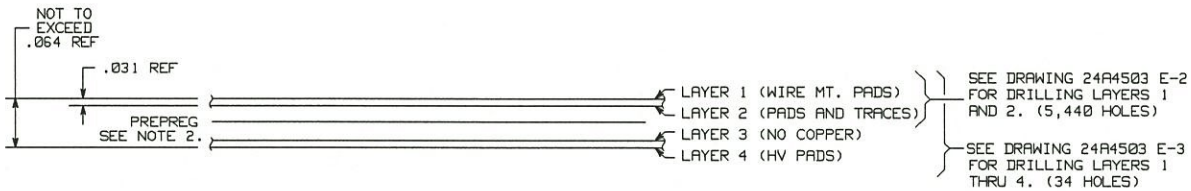
REV.	CHANGES	DRAWN	DATE	CHKD.	DATE





NOTES:

1. BOARD MATERIAL: .031 THICK G10 PER MIL-P-55617 FL-GEN 031C-1/1-A1A (1 OZ. COPPER EACH SIDE). THIS IS A MULTILAYER BOARD (4 LAYERS). TOTAL THICKNESS NOT TO EXCEED .064.
2. PREPREG THICKNESS TO BE DETERMINED BY MANUFACTURER PER IPC-L-109A OR MIL-P-55617.
3. PLEASE NOTE THAT THERE IS NO COPPER ON LAYER 3.
4. BOARD PANEL SIZE IS 10.500 +/-.010 X 28.100 +/-.005. SINGLE BOARD SIZE IS .472 +.000/-.010 X 28.100 +/-.005. DIMENSIONS ARE IN INCHES.
5. * = APPROXIMATE PLACEMENT OF .050 TABS. SLOTS TO BE .125 WIDE.
6. REFERENCE DRAWINGS:

24A4502 E-1	a000896e1	HOLE SCHEDULE - SINGLE BOARD
24A4503 E-2	a000896e2	HOLE SCHEDULE - PANEL OF 16 (BLIND VIAS)
24A4503 E-3	a000896e3	HOLE SCHEDULE - PANEL OF 16
24A4502 M-1	a000896m1	BOARD OUTLINE - SINGLE BOARD

DIST I:		TITLE	STAR TPC		
DIST II:			INNER SECTOR ELECTRONICS		
DIST III:			GATED GRID WIRE MOUNT BOARD - PANEL OF 16		
SHOWN ON			BOARD OUTLINE - 24A4501 U-2 (A000896U2)		
ACCOUNT NUMBER	8052-24	DRAWN STIRKKINEN	DATE 4/08/94	LAWRENCE BERKELEY LABORATORY	
SERIAL NUMBER		CHECKED	DATE	UNIVERSITY OF CALIFORNIA	
DATE ISSUED	NO. REQD.	APPROVED	DATE	OFFICE OF ELECTRONICS ENGINEERING	
DATE REQD.		ENGINEER	JIM HUNTER	FILE NO. a000896m2 / SIZE 3 / DRAWING NO. 24A4503 M-2	REV.
DEL. TO		SCALE	NONE	E2	SHEET 2 OF 2